

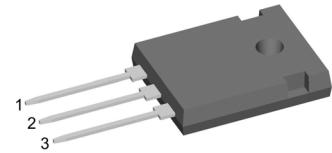
Standard Rectifier

V_{RRM} = 2x 1600 V
 I_{FAV} = 30 A
 V_F = 1,23 V

Phase leg

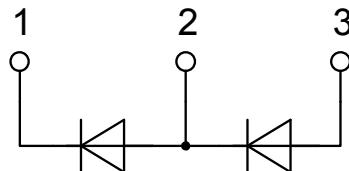
Part number

DMA30P1600HR



Backside: isolated

 E72873



Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very low forward voltage drop
- Improved thermal behaviour

Applications:

- Diode for main rectification
- For single and three phase bridge configurations

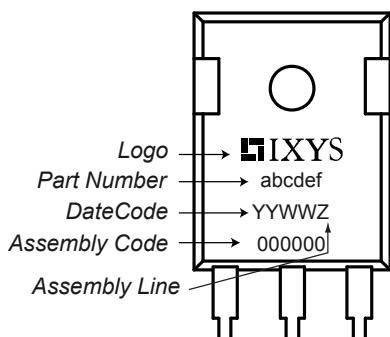
Package: ISO247

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Soldering pins for PCB mounting
- Backside: DCB ceramic
- Reduced weight
- Advanced power cycling

Rectifier

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
V_{RSM}	max. non-repetitive reverse blocking voltage	$T_{VJ} = 25^\circ C$			1700	V
V_{RRM}	max. repetitive reverse blocking voltage	$T_{VJ} = 25^\circ C$			1600	V
I_R	reverse current	$V_R = 1600 V$ $V_R = 1600 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 150^\circ C$		40 1,5	μA mA
V_F	forward voltage drop	$I_F = 30 A$ $I_F = 60 A$ $I_F = 30 A$ $I_F = 60 A$	$T_{VJ} = 25^\circ C$ $T_{VJ} = +02^\circ C$		1,28 1,57 1,23 1,63	V V V V
I_{FAV}	average forward current	$T_C = 105^\circ C$ 180° sine	$T_{VJ} = 175^\circ C$		30	A
V_{F0} r_F	threshold voltage slope resistance } for power loss calculation only		$T_{VJ} = 175^\circ C$		0,82 13,5	V mΩ
R_{thJC}	thermal resistance junction to case				1,3	K/W
R_{thCH}	thermal resistance case to heatsink			0,25		K/W
P_{tot}	total power dissipation		$T_C = 25^\circ C$		115	W
I_{FSM}	max. forward surge current	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$ $t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ C$ $V_R = 0 V$ $T_{VJ} = 150^\circ C$ $V_R = 0 V$		300 325 255 275	A
I^2t	value for fusing	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$ $t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ C$ $V_R = 0 V$ $T_{VJ} = 150^\circ C$ $V_R = 0 V$		450 440 325 315	A^2s A^2s A^2s A^2s
C_J	junction capacitance	$V_R = 400 V; f = 1 MH$	$T_{VJ} = 25^\circ C$	10		pF

Package ISO247			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	RMS current	per terminal			50	A
T_{VJ}	virtual junction temperature		-55		175	°C
T_{op}	operation temperature		-55		150	°C
T_{stg}	storage temperature		-55		150	°C
Weight				6		g
M_D	mounting torque		0,8		1,2	Nm
F_c	mounting force with clip		20		120	N
$d_{Spp/App}$	creepage distance on surface striking distance through air		2,7			mm
$d_{Spb/Abp}$	terminal to terminal terminal to backside		4,1			mm
V_{ISOL}	isolation voltage	$t = 1$ second $t = 1$ minute	3600 50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA	3000		V V

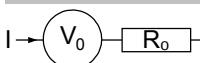
Product Marking**Part description**

D = Diode
 M = Standard Rectifier
 A = (up to 1800V)
 30 = Current Rating [A]
 P = Phase leg
 1600 = Reverse Voltage [V]
 HR = ISO247 (3)

Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DMA30P1600HR	DMA30P1600HR	Tube	30	512442

Equivalent Circuits for Simulation

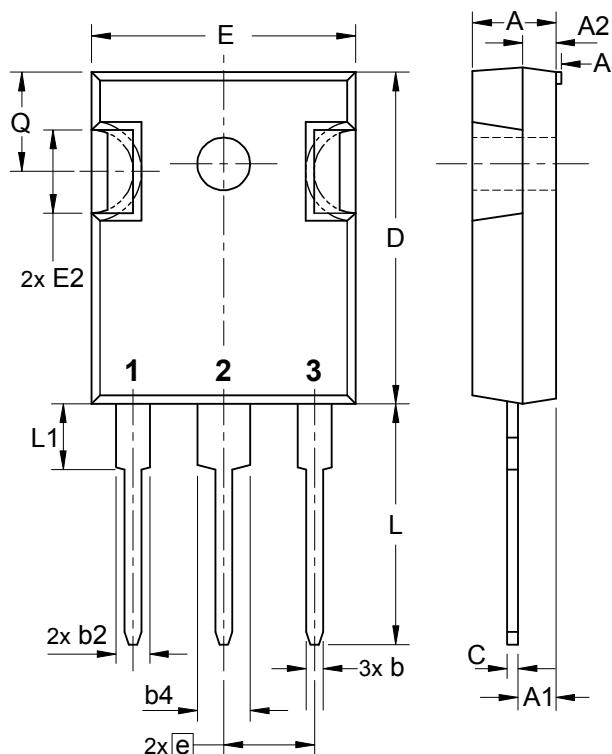
* on die level

 $T_{VJ} = 175$ °C

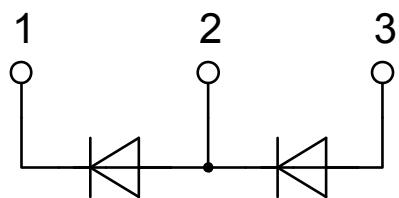
Rectifier

$V_{0\max}$ threshold voltage 0,82 V
 $R_{0\max}$ slope resistance * 10,9 mΩ

Outlines ISO247



Dim.	Millimeter		Inches	
	min	max	min	max
A	4.70	5.30	0.185	0.209
A1	2.21	2.59	0.087	0.102
A2	1.50	2.49	0.059	0.098
A3	typ. 0.05		typ. 0.002	
b	0.99	1.40	0.039	0.055
b2	1.65	2.39	0.065	0.094
b4	2.59	3.43	0.102	0.135
c	0.38	0.89	0.015	0.035
D	20.79	21.45	0.819	0.844
D1	typ. 8.90		typ. 0.350	
D2	typ. 2.90		typ. 0.114	
D3	typ. 1.00		typ. 0.039	
E	15.49	16.24	0.610	0.639
E1	typ. 13.45		typ. 0.530	
E2	4.31	5.48	0.170	0.216
E3	typ. 4.00		typ. 0.157	
e	5.46	BSC	0.215	BSC
L	19.80	20.30	0.780	0.799
L1	-	4.49	-	0.177
Ø P	3.55	3.65	0.140	0.144
Q	5.38	6.19	0.212	0.244
S	6.14	BSC	0.242	BSC



Rectifier

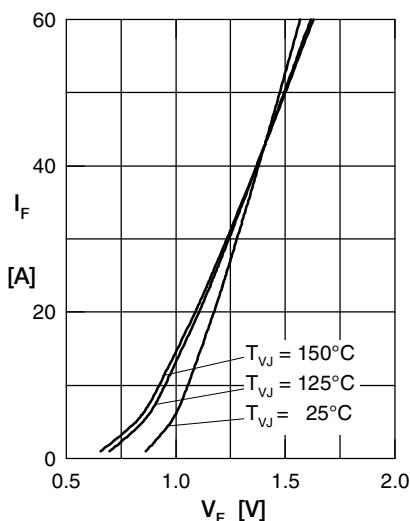


Fig. 1 Forward current versus voltage drop per diode

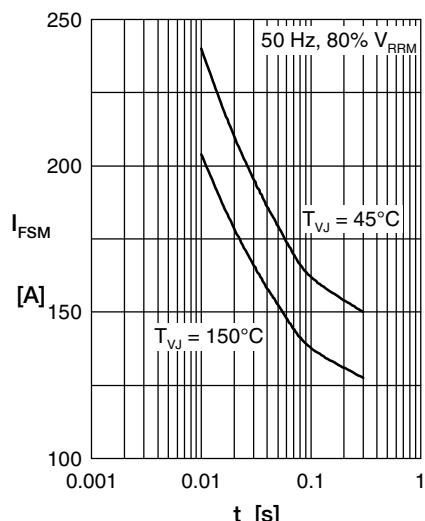


Fig. 2 Surge overload current vs. time per diode

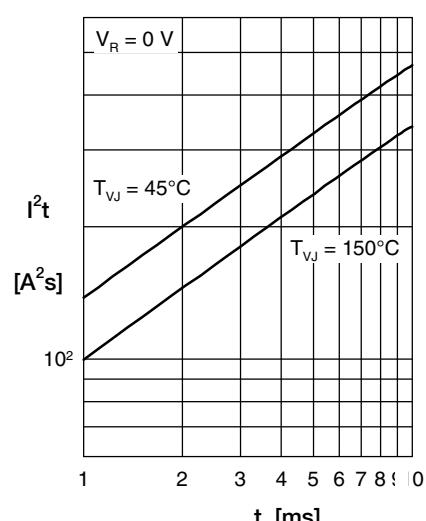


Fig. 3 I^2t versus time per diode

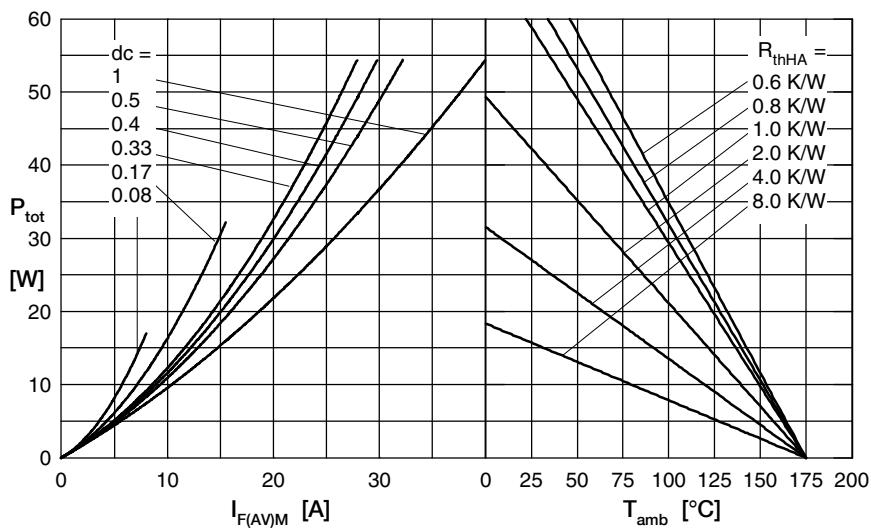


Fig. 4 Power dissipation vs. direct output current and ambient temperature per diode

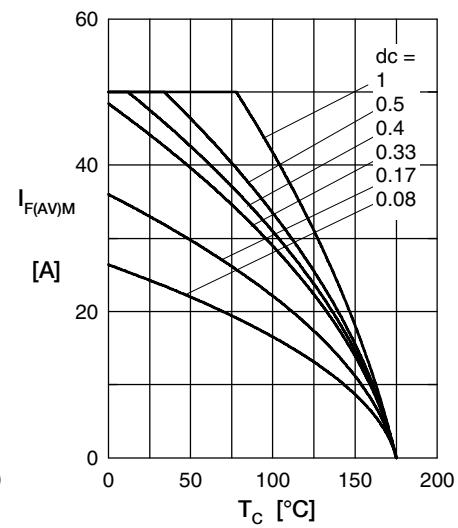


Fig. 5 Max. forward current vs. case temperature per diode

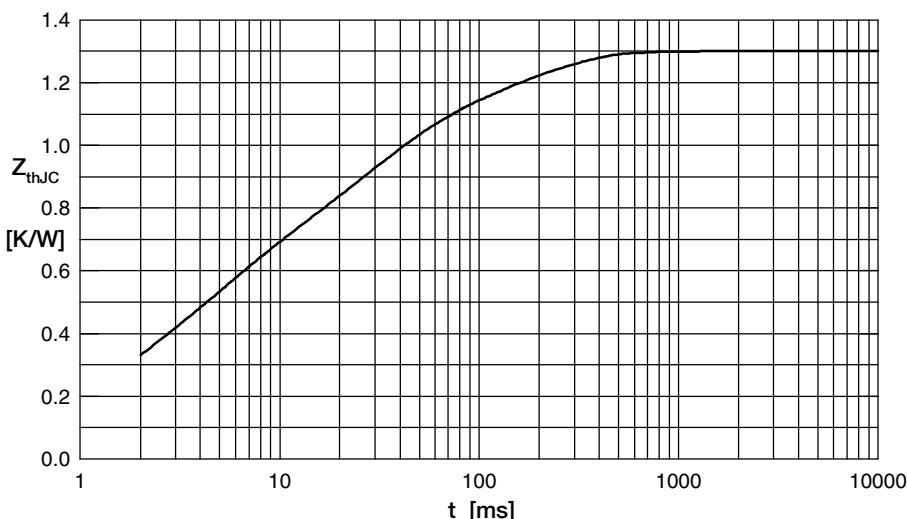


Fig. 6 Transient thermal impedance junction to case vs. time per diode

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.060	0.0004
2	0.170	0.0020
3	0.310	0.0040
4	0.470	0.0240
5	0.290	0.1500